

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc6244hvcms8#pbf

(Engineering Calculation)

MSOP

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TOTAL MASS (g) : 0.026844

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001633 | 1000000 | 60832.8984375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.006206 | 580000 | 231187.390625 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.004494 | 420000 | 167411.546875 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.010700 | 1000000 | 398598.9375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 26450.0175781 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 26450.0175781 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 3203.69213867 | | |
| | | Internal Plating Total: | | | | 0.000086 | 1000000 | 3203.69213867 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000602 | 750000 | 22425.8457031 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000201 | 250000 | 7487.69921875 | | |
| Die Attach Total: | | | | 0.000803 | 1000000 | 29913.5449219 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.001659 | 130000 | 61801.4570312 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.010591 | 830000 | 394538.4375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000447 | 35000 | 16651.75 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000064 | 5000 | 2384.14306641 | | |
| | | Encapsulation Total: | | | | 0.012761 | 1000000 | 475375.78125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000151 | 1000000 | 5625.08789062 | | |
| | | | | | TOTAL MASS (g) : | 0.026844 | | |